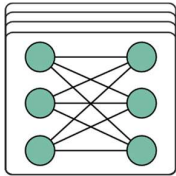




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TEMPO

Technologies and hardware for neuromorphic computing

Deliverable

D2.7 – SNN/DNN vs updated Tech.Spec. Table

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1. Publishable summary

This deliverable is a joint report covering the updated specification table, which has been covered before in D2.6 between Infineon AG and Robert Bosch GmbH. The scope is the definition of technical requirements towards emerging memories used as weights in SNNs and DNNs.

Infineon AG has been hereby focused on specifying the requirements for the SNN ASIC, which is developed in the Tempo project by them for consumer applications.

Robert Bosch GmbH has been working on defining the technical specification and requirements for embedded NVMs used in Automotive ASICs with respect to automotive reliability, quality, safety and security requirements. In addition to the report summarizing the general requirements and the assessment of MRAM and OxRAM as potential embedded NVM solutions for Automotive ASICs, FeFET was analyzed for Automotive ASICs.